



YEA SHIN TECHNOLOGY CO., LTD

YS8205AOE

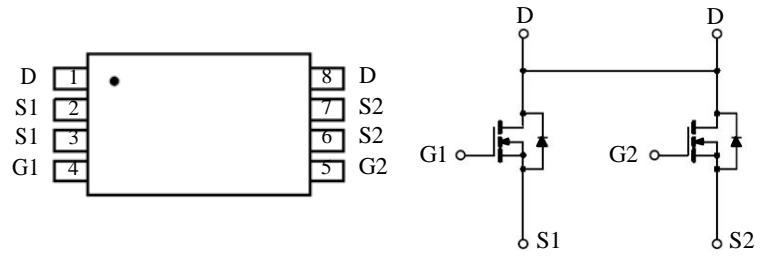
Dual N-Channel Enhancement MOSFET

VDS= 20V, ID= 6A

**Features**

Super high dense cell trench
design for low R_{DS(on)}.

Rugged and reliable.

TSSOP-8 Dual Pin Configuration**Applications**

Ideal for Li ion battery pack application.

Marking : 8205A

ABSOLUTE MAXIMUM RATING (T_A = 25 °C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	± 8	V
Drain Current-Continuous ^a @ T _A = 25 °C -Pulse ^b	I _D	6	A
	I _{DM}	24	A
Drain-Source Diode Forward Current ^a	I _S	1.7	A
Maximum Power Dissipation ^a	P _D	1.5	W
		0.96	
Operating Junction and Storage Temperature Range	T _J , T _{STG}	- 55 to 150	°C

THERMAL CHARACTERISTICS

Thermal Resistance,Junction-to-Ambient ^a	R _{thJA}	83	°C/W
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Note

a. Surface Mounted on FR4 Board , t = 10sec .

b. Pulse width limited by maximum junction temperature.

DEVICE CHARACTERISTICS

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Electrical Characteristics (T_j=25°C, unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ ^c	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BVDSS	V _{GS} = 0V, I _D = 250uA	20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20V, V _{GS} = 0V			1	uA
Gate-Body Leakage	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0V			±100	nA
ON CHARACTERISTICS^b						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	0.5	0.9	1.5	V
Drain-Source On-State Resistance	R _{DSS(on)}	V _{GS} = 4V, I _D = 6A		23	27	m
		V _{GS} = 2.5V, I _D = 5.2A		30	38	
DRAIN-SOURCE DIODE CHARACTERISTICS^b						
Diode Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 1.7A			1.2	V
DYNAMIC CHARACTERISTICS^c						
Input Capacitance	C _{ISS}	V _{DS} = 8V, V _{GS} = 0V f = 1.0MHz		522		pF
Output Capacitance	C _{OSS}			124		pF
Reverse Transfer Capacitance	C _{RSS}			148		pF
SWITCHING CHARACTERISTICS^c						
Turn-On Delay Time	t _{D(ON)}	V _{DD} = 10V, I _D = 1A V _{GEN} = 4.5V R _L = 10 R _{GEN} = 6		10		ns
Rise Time	t _r			8.2		ns
Turn-Off Delay Time	t _{D(OFF)}			2.5		ns
Fall Time	t _f			6		ns
Total Gate Charge	Q _g	V _{DS} = 10V, I _D = 3A V _{GS} = 4.5V		6.1		nC
Gate-Source Charge	Q _{gs}			1.7		nC
Gate-Drain Charge	Q _{gd}			1.4		nC

Note :

b. Pulse Test : Pulse width 300us , Duty Cycle 2% .

c. Guaranteed by design , not subject to production testing .

DEVICE CHARACTERISTICS

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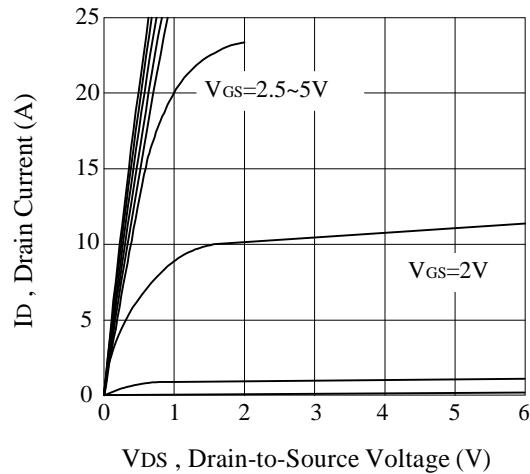


Figure 1. Output Characteristics

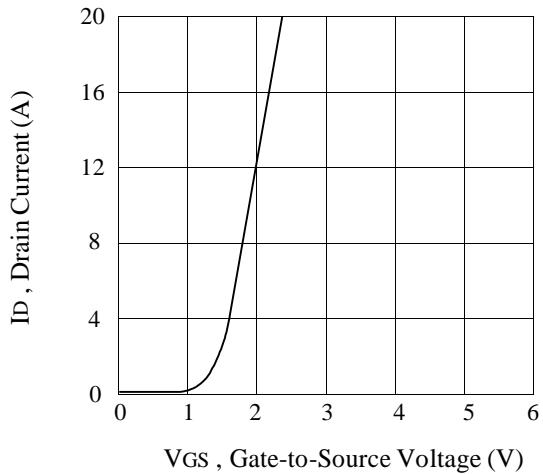


Figure 2. Transfer Characteristics

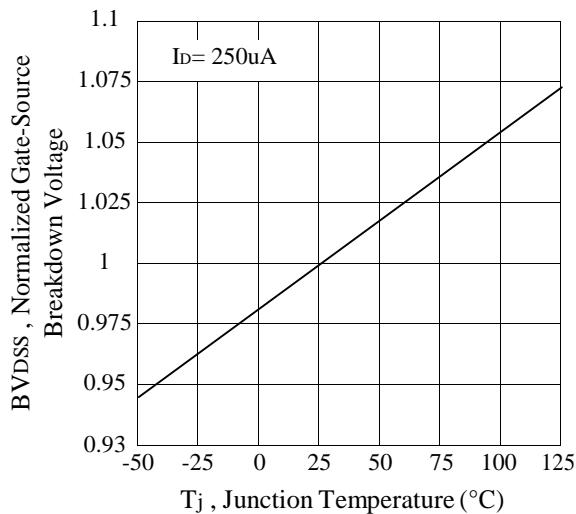


Figure 3. Breakdown Voltage Variation with Temperature

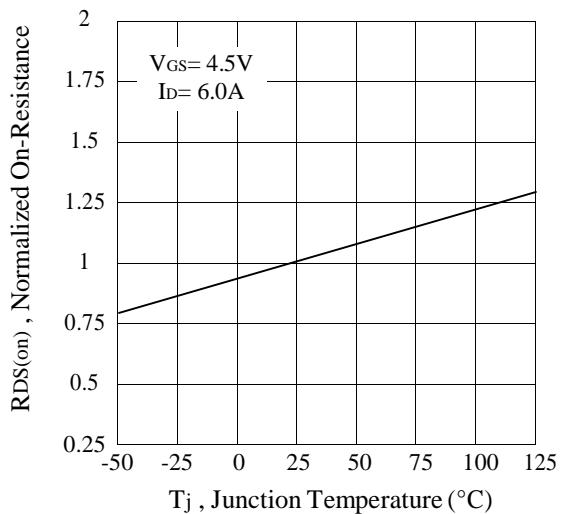


Figure 4. On-Resistance Variation with Temperature

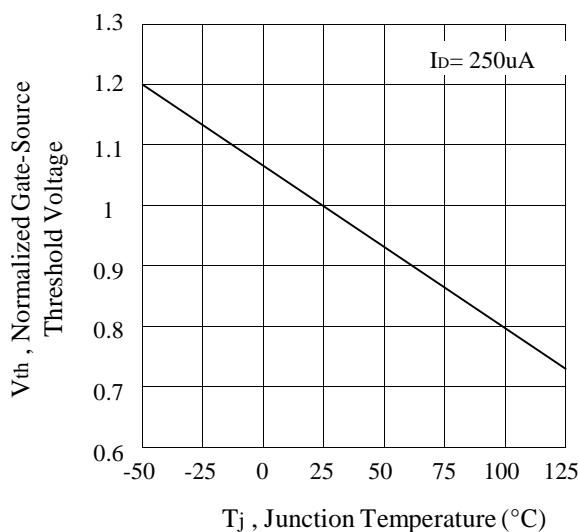


Figure 5. Gate Threshold Variation with Temperature

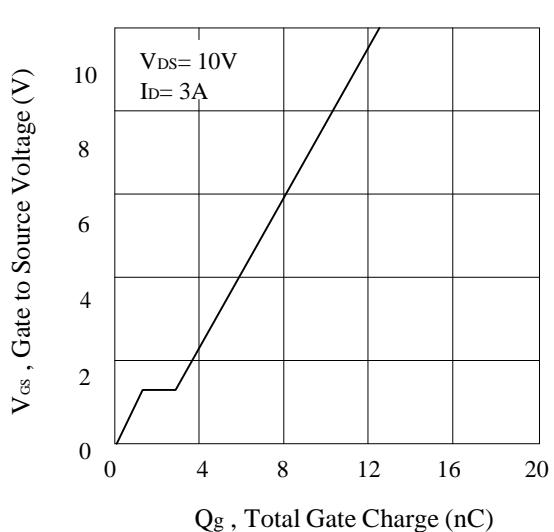
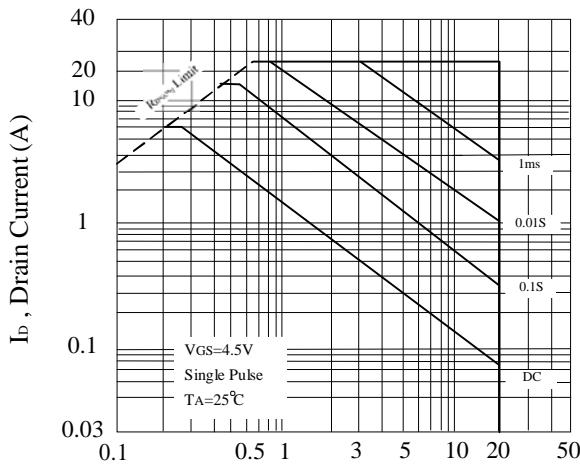


Figure 6. Gate Charge

DEVICE CHARACTERISTICS

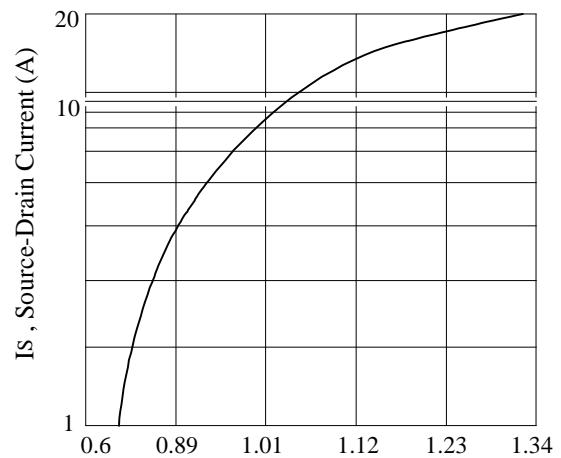
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V_{DS}, Drain-Source Voltage (V)

Figure 7. Maximum Safe Operating

Area



V_{SD}, Body Diode Forward Voltage (V) Figure 8.

Body Diode Forward Voltage Variation

with Source Current

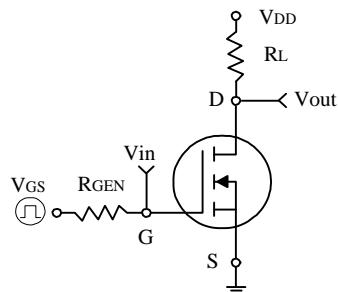


Figure 9. Switching Test Circuit and Switching Waveforms

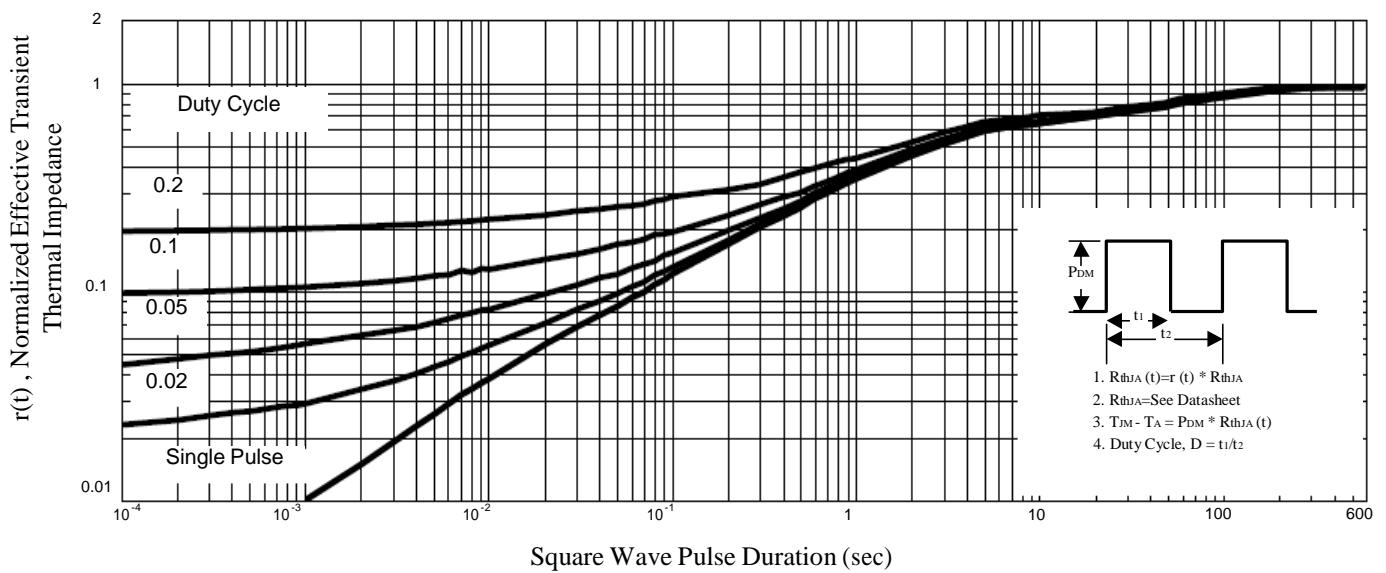
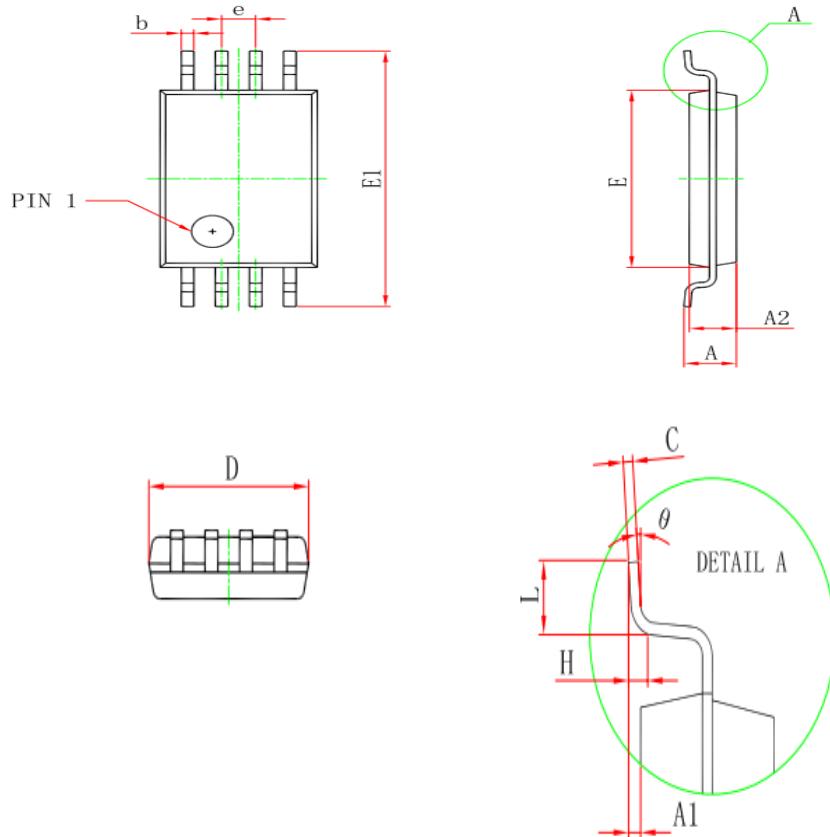


Figure 10. Normalized Thermal Transient Impedance Curve

PACKAGE OUTLINE & DIMENSIONS

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TSSOP-8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
D	2.900	3.100	0.114	0.122
E	4.300	4.500	0.169	0.177
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
E1	6.250	6.550	0.246	0.258
A		1.200		0.047
A2	0.800	1.000	0.031	0.039
A1	0.050	0.150	0.002	0.006
e	0.65 (BSC)		0.026 (BSC)	
L	0.500	0.700	0.020	0.028
H	0.25(TYP)		0.01(TYP)	
θ	1°	7°	1°	7°